

	FSK for digital data and F FM/FSK demodulation en Low current consumption Switchable LNA gain for a AFC feature allows wide	carrier frequency acceptance range gth indication and ASK detection)r
Oi	rdering Informatio	חי	
Pa	rt No.	Temperature Range	Package
TH	17110	-40 °C to 85 °C	LQFP44
	Oplication Example General digital and analo Low-power telemetry Alarm and security syster Keyless car and central to Pagers	g 315 MHz or 433 MHz ISM band usage	
Τε	echnical Data Ove	rview	
	Temperature range: -40 °C Operating current: 6.5 m/standby current: < 100 n/sensitivity: -111 dBm 1) Sensitivity: -104 dBm 2) WRange of first IF: 10 MHz Range of second IF: 455 Maximum input level: -10 Image rejection: > 65 dB Spurious emission: < -70	V to 5.5 V for double conversion and 2.7 V to 5.0 C to +85 °C A at low gain and 8.2 mA at high gain mode A with 40 kHz second IF filter BW (incl. SAW from the 150 kHz second IF filter BW (incl. SAW from to 80 MHz kHz to 21.4 MHz double double double double at ASK and 0 dBm at FSK (e.g. with SAW front-end filter and at 10.7 MHz	nt-end filter loss) nt-end filter loss)

 $^{1)}$ at $\pm~$ 8 kHz FSK deviation, BER = $3\cdot10^{\text{-}3}$ and phase-coincidence demodulation $^{2)}$ at $\pm~50$ kHz FSK deviation, BER = $3\cdot10^{\text{-}3}$ and phase-coincidence demodulation

☐ Frequency deviation range: ±5 kHz to ±120 kHz

☐ Maximum analog modulation frequency: 15 kHz

☐ Maximum data rate: 80 kbit/s NRZ

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General Description

The TH7110 receiver IC consists of the following building blocks:

- PLL synthesizer (PLL SYNTH) for generation of the first and second local oscillator signals LO1 and LO2
- Parts of the PLL SYNTH are the high-frequency VCO1, the feedback dividers DIV_8 and DIV_2, a phase-frequency detector (PFD) with charge pump (CP) and a crystal-based reference oscillator (RO)
- Low-noise amplifier (LNA) for high-sensitivity RF signal reception
- First mixer (MIX1) for down-conversion of the RF signal to the first IF (IF1)
- second mixer (MIX2) for down-conversion of the IF1 to the second IF (IF2)
- IF amplifier (IFA) to amplify and limit the IF2 signal and for RSSI generation
- Phase coincidence demodulator (DEMOD) with third mixer (MIX3) to demodulate the IF signal
- Operational amplifier (OA) for data slicing, filtering, ASK detection and automatic-frequency control (AFC)
- Bias circuitry for bandgap biasing and circuit shutdown

With the TH7110 receiver chip, various circuit configurations can be arranged in order to meet a number of different customer requirements. For FM/FSK reception the IF tank used in the phase coincidence demodulator can be constituted either by a ceramic resonator or an LC tank (optionally with varactor to create an AFC circuit). In PLL demodulator configuration, the multiplier MIX3 forms a phase comparator. In ASK configuration, the RSSI signal is feed to an ASK detector, which is constituted by the operational amplifier. The second VCO (VCO2) can be used either as the VCO of a PLL demodulator or as the LO2 source of a second external PLL in a multi-channel system. The following table briefly summarizes the various configurations.

	Single-conversion configuration	Double-conversion configuration		
FM/FSK	narrow-band RX with ceramic demodulation tank	narrow-band RX with ceramic demodulation tank		
FM/FSK	wide-band RX with LC demod. tank and AFC	wide-band RX with LC demod. tank and AFC		
FM/FSK	extended sensitivity RX with PLL demodulator	extended sensitivity RX with PLL demodulator		
FM/FSK		multi-channel RX with ceramic demodulation tank and external channel synthesizer		
ASK	RX with RSSI-based demodulation	RX with RSSI-based demodulation		
ASK		RX with RSSI-based demodulation and external channel synthesizer		

The preferred superheterodyne configuration is **double conversion** where MIX1 and MIX2 are driven by the internal local oscillator signals LO1 and LO2, respectively. This allows a **high degree of image rejection**, achieved in conjunction with an RF front-end filter. Efficient RF front-end filtering is realized by using a SAW, ceramic or helix filter in front of the LNA and by adding a LC filter at the LNA output.

It is also possible to use the TH7110 in **single-conversion** configuration. This can be achieved by switching the LO2 input of MIX2 from the on-chip PLL synthesizer to the pin IN_MIX2 by means of an internal switch (done via pin SW_MIX2). Now MIX2 operates as an amplifier for the IF1 signal if an external pull-down resistor at pin IN_MIX2 is added.

The same setting of MIX2 can be used for **multi-channel applications**. In this situation IN_MIX2 must be driven by an external LO2 signal. This signal can be generated by the VCO2, which is mainly a bipolar transistor that can be configured as a varactor-tuned VCO. Furthermore, a second external PLL for channel selection via LO2 tuning is required. This may be arranged by using a PLL synthesizer chip that can be controlled through a 3-wire bus serial interface. The reference signal for the external PLL synthesizer can be directly taken from the crystal-based reference oscillator RO.

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Block Diagram

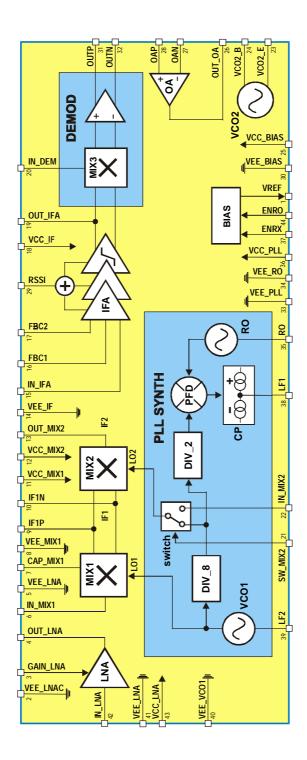


Fig. 1: TH7110 block diagram

Frequency Planning

Frequency planning is straightforward for single-conversion applications because there is only one IF that might be chosen, and then the only possible choice is low-side or high-side injection of the LO1 signal (which is now the one and only LO signal in the receiver).

The receiver's double-conversion architecture requires careful frequency planning. Besides the desired RF input signal, there are a number of spurious signals that may cause an undesired response at the output. Among them are the image of the RF signal (that must be suppressed by the RF front-end filter), spurious signals injected to the first IF (IF1) and their images which could be mixed down to the same second IF (IF2) as the desired RF signal (they must be suppressed by the LC filter at IF1 and/or by low-crosstalk design).

By configuring the TH7110 for double conversion and using its internal PLL synthesizer with fixed feedback divider ratios of N1 = 8 (DIV_8) and N2 = 2 (DIV_2), four types of down-conversion are possible: low-side injection of LO1 and LO2 (**low-low**), LO1 low-side and LO2 high-side (**low-high**), LO1 high-side and LO2 low-side (**high-low**) or LO1 and LO2 high-side (**high-high**). The following table summarizes some equations that are useful to calculate the crystal reference frequency (REF), the first IF (IF1) and the VCO1 or first LO frequency (LO1), respectively, for a given RF and second IF (IF2).

Injection type	high-high	low-low	high-low	low-high
REF	(RF – IF2)/14	(RF – IF2)/18	(RF + IF2)/14	(RF + IF2)/18
LO1	16∙REF	16∙REF	16∙REF	16∙REF
IF1	LO1 – RF	RF – LO1	LO1 – RF	RF – LO1
LO2	2•REF	2•REF	2•REF	2•REF
IF2	LO2 – IF1	IF1 – LO2	IF1 – LO2	LO2 – IF1

The following table depicts generated, desired, possible images and some undesired signals considering the examples of 315 MHz and 433.6 MHz RF reception at IF2 = 10.7 MHz.

Signal type	RF = 315 MHz	RF = 315 MHz	RF = 315 MHz	RF = 315 MHz	RF = 433.6 MHz	RF = 433.6 MHz	RF = 433.6 MHz	RF = 433.6 MHz
Injection type	high-high	low-low	high-low	low-high	high-high	low-low	high-low	low-high
REF / MHz	21.73571	16.90556	23.26429	18.09444	30.20714	23.49444	31.73571	24.68333
LO1 / MHz	347.77143	270.48889	372.22857	289.51111	483.31429	375.91111	507.77143	394.93333
IF1 / MHz	32.77143	44.51111	57.22857	25.48889	49.71429	57.68889	74.17143	38.66667
LO2 / MHz	43.47143	33.81111	46.52857	36.18889	60.41429	46.98889	63.47143	49.36667
RF image/MHz	380.54286	225.97778	429.45714	264.02222	533.02857	318.22222	581.94286	356.26667
IF1 image/MHz	54.17143	23.11111	35.82857	46.88889	71.11429	36.28889	52.77143	60.06667

The selection of the reference crystal frequency is based on some assumptions. As for example: the first IF and the image frequencies should not be in a radio band where strong interfering signals might occur (because they could represent parasitic receiving signals), the LO1 signal should be in the range of 300 MHz to 430 MHz (because this is the optimum frequency range of the VCO1). Furthermore the first IF should be as high as possible to achieve highest RF image rejection. The columns in bold depict the selected frequency plans to receive at 315 MHz and 433.6 MHz, respectively.

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Pin Definition and Description

Pin No.	Name	I/O Type	Functional Schematic	Description
1	VREF	analog output	VREF VCC F	reference voltage output, approx. 1.23V
4	OUT_LNA	analog output	VCC P OUT_LNA	LNA open-collector output, to be connected to external LC tank that resonates at RF
42	IN_LNA	analog input	IN_LNA 5k VEE	LNA input, approx. 26Ω single-ended
2	VEE_LNAC	ground	VEE_LNAC VEE	ground of LNA core (cascode)
3	GAIN_LNA	analog input	GAIN_LNA 400Ω VEE	LNA gain control (CMOS input with hysteresis)
5	VEE_LNA	ground		LNA biasing ground
6	IN_MIX1	analog input	VCC 13Ω	MIX1 input, approx. 33Ω single-ended
7	CAP_MIX1	analog I/O	CAP_MIX1 VCC 40μA	connection for MIX1 blocking capacitor
8	VEE_MIX1	ground		MIX1 ground
9	IF1P	analog I/O	F1P	open-collector output, to be connected to external LC tank that resonates at first IF
10	IF1N	analog I/O	2x500μA VEE	open-collector output, to be connected to external LC tank that resonates at first IF



Pin No.	Name	I/O Type	Functional Schematic	Description
11	VCC_MIX1	supply		MIX1 positive supply
12	VCC_MIX2	supply		MIX2 positive supply
13	OUT_MIX2	analog output	OUT_MIX2 130Ω VCC 6.8k	MIX2 output, approx. 330Ω output impedance
14	VEE_IF	ground		ground of MIX2, IFA and DEMOD
15	IN_IFA	analog input	IN_IFA FBC1	IFA input, approx. 2.2kΩ input impedance
16	FBC1	analog I/O	15 VEE 2.2k 2.2k VCC D VEE	to be connected to external IFA feedback capacitor
17	FBC2	analog I/O	FBC2 VEE	to be connected to external IFA feedback capacitor
18	VCC_IF	supply		positive supply for IFA, DEMOD and VCO2
19	OUT_IFA	analog I/O	OUT_IFA VCC 40µA	IFA output and MIX3 input (of DEMOD)
20	IN_DEM	analog input	IN_DEM VCC 47k	DEMOD input, to MIX3 core
21	SW_MIX2	digital input	SW_MIX2 400Ω VEE	input selection for LO2 input port of MIX2



Pin No.	Name	I/O Type	Functional Schematic	Description
22	IN_MIX2	analog input	VCC 11 IN_MIX2 22 840Ω VEE 20μA	external LO2 input port of MIX2, approx. 1kΩ single-ended
24	VCO2_B	analog input	VCO2_B VCC TO VCC 47k	VCO2 input, base of a bipolar transistor
23	VCO2_E	analog output	VCO2_E VEE	VCO2 output, emitter of a bipolar transistor
25	VCC_BIAS	supply		positive supply of general bias system and OA
26	OUT_OA	analog output	OUT_OA 5000	OA output, 40uA current drive capability
27	OAN	analog input	OAN 50Ω OAP	negative OA input, input voltage limited to approx. 0.7 V _{pp} between pins OAP and OAN
28	OAP	analog input	27 VEE VEE 28	positive OA input, input voltage limited to approx. 0.7 V _{pp} between pins OAP and OAN
29	RSSI	analog output	RSSI 50Ω I (Pi) 29 36k	RSSI output, for RSSI and ASK detection, approx. 36kΩ output impedance
30	VEE_BIAS	ground		ground for general bias system and OA



Pin No.	Name	I/O Type	Functional Schematic	Description
31	OUTP	analog output	OUTP 50Ω	FSK/FM positive output, output impedance of $100kΩ$ to $300kΩ$
32	OUTN	analog output	31 32 20μΑ 20μΑ	FSK/FM negative output, output impedance of $100k\Omega$ to $300k\Omega$
33	VEE_PLL	ground		ground of dividers and PFD
34	VEE_RO	ground		RO ground
35	RO	analog input	RO SOR SOR SOR SOR SOR SOR SOR SOR SOR S	RO input, Colpitts type oscillator with internal feedback capacitors
36	VCC_PLL	supply		positive supply of RO, DIV, PFD and charge pump
37	ENRX	digital input	ENRX ENRO 1.5k	mode control input (CMOS input)
44	ENRO	digital input	37 44 VEE VEE VEE	mode control input (CMOS input)
38	LF1	analog output	VCC 200Ω 18 18 18 18 18 18 18 18 18 18 18 18 18	charge pump output
39	LF2	analog input	VCC 400Ω 4p 4p	VCO1 control input
40	VEE_VCO1	ground		ground of VCO1 and charge pump
41	VEE_LNA	ground		ground of LNA biasing
43	VCC_LNA	supply		positive supply of LNA biasing



Technical Data

Mode Configurations

ENRX	ENRO	Mode	Description
0	0	SBY	standby mode
0	1	RO only	only reference oscillator active
1	0	ON	entire chip active
1	1	ON	entire chip active

Note: ENRX and ENRO are pulled down internally

Second Mixer Input

IN_MIX2 SW_MIX2		Mode
External LO2	0	double conversion with external LO2
Ext. pull-down res. (15 k Ω)	0	single conversion
N/C	1	double conversion with internal LO2

LNA Gain Control

V _{GAIN_LNA}	Mode	Description
< 0.8 V	HIGH GAIN	LNA set to high gain by voltage at GAIN_LNA
> 1.4 V	LOW GAIN	LNA set to low gain by voltage at GAIN_LNA

Note: hysteresis between gain modes to ensure stability

Absolute Maximum Ratings

Parameter	Symbol	Condition / Note	Min	Max	Unit
Supply voltage	V _{cc}		0	7.0	V
Input voltage	V_{IN}		- 0.3	V _{CC} +0.3	V
Input RF level	P _{imax}	no damage		10	dBm
Storage temperature	T _{STG}		-40	+125	°C
Electrostatic discharge	ESD	human body model, MIL STD 833D method 3015.7, all pins			
		except OUT_IFA	-500	+500	V
		pin OUT_IFA	-500	+250	V

Normal Operating Conditions

Parameter	Symbol	Condition	Min	Max	Unit
Supply voltage for double conv.	V _{cc, DC}		2.5	5.5	V
Supply voltage for single conv.	V _{cc, SC}		2.7	5.5	V
Operating temperature	Ta		-40	+85	°C
Input frequency	f _i		300	450	MHz
Frequency deviation	Δf	at FM or FSK	±5	±120	kHz
FSK data rate	R _{FSK}	NRZ		40	kbit/s
FM bandwidth	f _m			15	kHz
ASK data rate	R _{ASK}	NRZ		80	kbit/s

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DC Characteristics

all parameters under normal operating conditions, unless otherwise stated; typical values at T_a = 23 °C and V_{cc} = 3 V

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Standby current	I _{SBY}	ENRX=0			100	nA
Total supply current at low gain	I _{cc, low}	ENRX=1, LNA at LOW GAIN	5.0	6.5	8.0	mA
Total supply current at high gain	I _{cc, high}	ENRX=1, LNA at HIGH GAIN	6.5	8.2	10.0	mA
Opamp input offset voltage	V_{offs}		-20		20	mV
Opamp input offset current	I _{offs}	$I_{OAP} - I_{OAN}$	-50		50	nA
Opamp input bias current	I _{bias}	$0.5 * (I_{OAP} + I_{OAN})$	-100		100	nA
RSSI voltage at low input level	$V_{RSSI, low}$	P _i = -65 dBm, LNA at LOW GAIN	0.5	1.0	1.5	V
RSSI voltage at high input level	V _{RSSI, high}	P _i = -35 dBm, LNA at LOW GAIN	1.25	1.9	2.45	V

AC System Characteristics

all parameters under normal operating conditions, unless otherwise stated; all parameters based on test circuits for FSK (Fig. 2), FM (Fig. 4) and ASK (Fig. 5), respectively; typical values at T_a = 23 °C and V_{cc} = 3 V, RF at 433.6 MHz, second IF at 10.7 MHz

Parameter	Symbol	Condition	Min	Тур	Max	Unit
Start-up time – fast mode FSK/FM	T _{fast}	ENRX from 0 to 1, ENRO = 1, valid data at output			0.4	ms
Start-up time – slow mode FSK/FM	T _{slow}	ENRX from 0 to 1, ENRO = 0, valid data at output			0.9	ms
Start-up time – ASK	T _{ASK}	depends on ASK de- tector time constant and start-up mode, valid data at output			R3•C13 + T _{fast} (or T _{slow})	ms
Input sensitivity – FSK (narrow band)	P _{min, n}	$B_{IF2} = 40kHz$ $\Delta f = \pm 15kHz$ (FSK/FM) $BER \le 3.10^{-3}$		-111		dBm
Input sensitivity – FSK (wide band)	P _{min, w}	$B_{IF2} = 150 \text{kHz}$ $\Delta f = \pm 50 \text{kHz} \text{ (FSK/FM)}$ $BER \le 3.10^{-3}$		-104		dBm
Input sensitivity – ASK (narrow band)	P _{minA, n}	$B_{IF2} = 40kHz$ BER $\leq 3.10^{-3}$		-109		dBm
Input sensitivity – ASK (wide band)	P _{minA, w}	$B_{IF2} = 150kHz$ BER $\leq 3.10^{-3}$		-106		dBm
Maximum input signal – FSK/FM	P _{max, FM}	BER ≤ 3·10 ⁻³ LNA at LOW GAIN		0		dBm
Maximum input signal – ASK	P _{max, ASK}	BER ≤ 3·10 ⁻³ LNA at LOW GAIN		-10		dBm
Spurious emission	P _{spur}				-70	dBm
Image rejection	ΔP_{imag}			65		dB
Blocking immunity	ΔP_{block}	$\Delta f_{block} > \pm 2MHz$, note 1		57		dB
VCO gain	K _{VCO}			250		MHz/V
Charge pump current	I _{CP}			60		μA

Notes: 1. desired signal with FSK/FM or ASK modulation, CW blocking signal



Test Circuits

FSK Reception

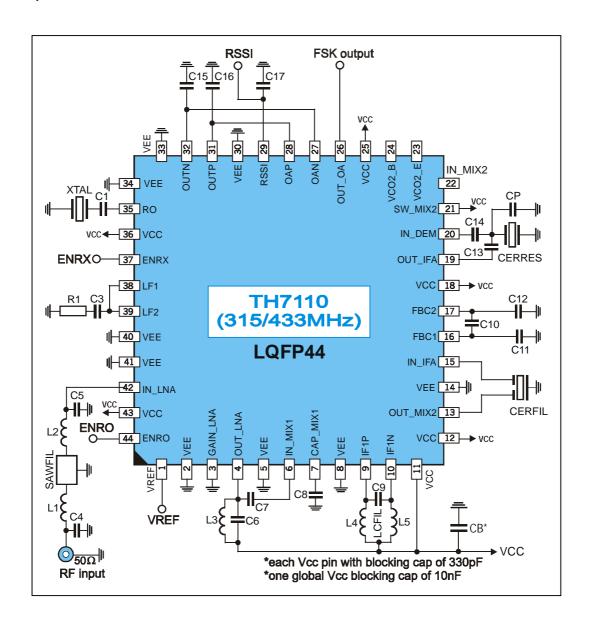


Fig. 2: Test circuit for FSK reception

FSK test circuit component list to Fig. 2

Part	Size	Value / Type	Tolerance	Description			
C1	0805	15 pF	±10%	crystal series capacitor			
C3	0805	1 nF	±10%	loop filter capacitor			
C4	0603	3.3 pF	±5%	capacitor to match to SAW filter input			
C5	0603	3.3 pF	±5%	capacitor to match to SAW filter output			
C6	0603	4.7 pF	±5%	LNA output tank capacitor			
C7	0603	2.2 pF	±5%	MIX1 input matching capacitor			
C8	0603	330 pF	±10%	MIX1 blocking capacitor			
C9	0603	27 pF	±5%	IF1 tank capacitor			
C10	0805	33 nF	±10%	IFA feedback capacitor			
C11	0603	1 nF	±10%	IFA feedback capacitor			
C12	0603	1 nF	±10%	IFA feedback capacitor			
C13	0603	1.5 pF	±5%	DEMOD phase-shift capacitor			
C14	0603	680 pF	±10%	DEMOD coupling capacitor			
CP	0805	10 –12 pF	±5%	CERRES parallel capacitor			
C15	0805	10 – 47 pF	±5%	demodulator output low-pass capacitor, depending on data rate			
C16	0805	10 – 47 pF	±5%	demodulator output low-pass capacitor, depending on data rate			
C17	0603	330 pF	±10%	RSSI output low-pass capacitor			
R1	0805	10 kΩ	±10%	loop filter resistor			
L1	0603	33 nH	±5%	inductor to match SAW filter			
L2	0603	33 nH	±5%	inductor to match SAW filter			
L3	0603	15 nH	±5%	LNA output tank inductor			
L4	0805	100 nH	±5%	IF1 tank inductor			
L5	0805	100 nH	±5%	IF1 tank inductor			
XTAL	HC49- SMD	23.49444 MHz @ RF = 433.6 MHz	±25ppm calibra- tion ±30ppm temp.	fundamental-mode crystal, C_{load} = 10 pF to 15pF, $C_{0, max}$ = 7 pF, $R_{m, max}$ = 50 Ω			
SAWFIL	QCC8C	B3555 @ RF = 433.6 MHz	$B_{3dB} = 860 \text{ kHz}$ $\pm 100 \text{ kHz}$ $(f_0 = 433.92 \text{ MHz})$	low-loss SAW filter from EPCOS			
CERFIL	leaded type	SFE10.7MFP @ B _{IF2} = 40 kHz	TBD	ceramic filter from Murata			
	SMD type	SFECV10.7MJS-A @ B_{IF2} = 150 kHz	±40 kHz				
CERRES	SMD type	CDACV10.7MG18-A		ceramic demodulator tank from Murata			

NIP - not in place, may be used optionally



FSK Circuit with AFC and Ceramic Resonator Tolerance Compensation

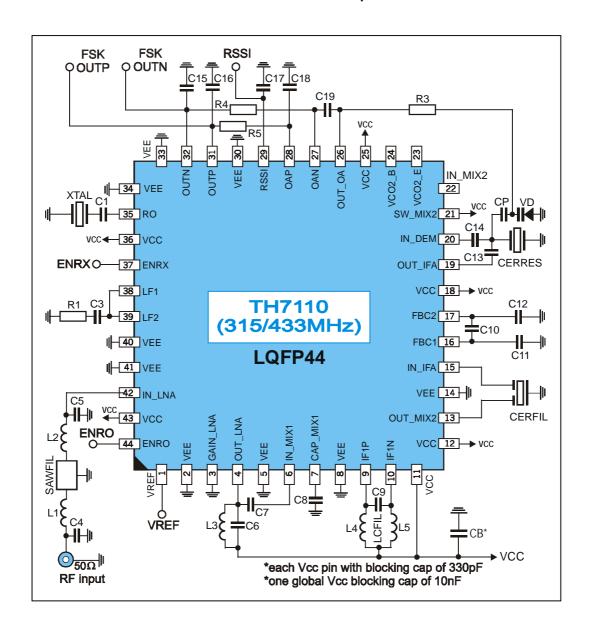


Fig. 3: Test circuit for FSK with AFC and resonator compensation

Circuit Feature

- ☐ Improves input frequency acceptance range up to RF_{nom} ±50 kHz
- ☐ Eliminates calibration tolerances of ceramic resonator
- ☐ Eliminates temperature tolerances of ceramic resonator
- Non-inverted and inverted CMOS-compatible outputs

FSK test circuit with AFC component list to Fig. 3

Part	Size	Value / Type	Tolerance	Description	
C1	0805	15 pF	±10%	crystal series capacitor	
C3	0805	1 nF	±10%	loop filter capacitor	
C4	0603	3.3 pF	±5%	capacitor to match to SAW filter input	
C5	0603	3.3 pF	±5%	capacitor to match to SAW filter output	
C6	0603	4.7 pF	±5%	LNA output tank capacitor	
C7	0603	2.2 pF	±5%	MIX1 input matching capacitor	
C8	0603	330 pF	±10%	MIX1 blocking capacitor	
C9	0603	27 pF	±5%	IF1 tank capacitor	
C10	0805	33 nF	±10%	IFA feedback capacitor	
C11	0603	1 nF	±10%	IFA feedback capacitor	
C12	0603	1 nF	±10%	IFA feedback capacitor	
C13	0603	1.5 pF	±5%	DEMOD phase-shift capacitor	
C14	0603	680 pF	±10%	DEMOD coupling capacitor	
CP	0805	27 pF	±5%	ceramic resonator loading capacitor	
C15	0805	10 – 47 pF	±5%	demodulator output low-pass capacitor, depending on data rate	
C16	0805	10 – 47 pF	±5%	demodulator output low-pass capacitor, depending on data rate	
C17	0603	330 pF	±10%	RSSI output low-pass capacitor	
C18		33 nF	±10%	integrator capacitor, fixed	
C19	0805	33 nF	±10%	integrator capacitor, @ 0.5 to 2 kbit/s NRZ	
		10 nF		integrator capacitor, @ 2 to 20 kbit/s NRZ	
		1 nF		integrator capacitor, @ 20 to 40 kbit/s NRZ	
R1	0805	10 kΩ	±10%	loop filter resistor	
R3	0805	100 kΩ	±10%	varactor diode biasing resistor	
R4	0805	680 kΩ	±10%	integrator resistor	
R5	0805	680 kΩ	±10%	integrator resistor	
L1	0603	33 nH	±5%	inductor to match SAW filter	
L2	0603	33 nH	±5%	inductor to match SAW filter	
L3	0603	15 nH	±5%	LNA output tank inductor	
L4	0805	100 nH	±5%	IF1 tank inductor	
L5	0805	100 nH	±5%	IF1 tank inductor	
VD	SOD-323	BB535		varactor diode from Infineon	
XTAL	HC49-	23.49444 MHz	±25ppm calibra-	fundamental-mode crystal, $C_{load} = 10 pF$ to 15pF,	
	SMD	@ RF = 433.6 MHz	tion ±30ppm temp.	$C_{0, \text{ max}} = 7 \text{ pF}, R_{\text{m, max}} = 50 \Omega$	
SAWFIL	QCC8C	B3555	B _{3dB} = 860 kHz	low-loss SAW filter from EPCOS	
		@ RF = 433.6 MHz	±100 kHz		
			$(f_0 = 433.92 \text{ MHz})$		
CERFIL	leaded	SFE10.7MFP	TBD	ceramic filter from Murata	
	type	@ $B_{IF2} = 40 \text{ kHz}$			
	SMD type	SFECV10.7MJS-A	±40 kHz		
		@ $B_{IF2} = 150 \text{ kHz}$			
CERRES	SMD type	CDACV10.7MG18-A		ceramic demodulator tank from Murata	

NIP - not in place, may be used optionally



FM Reception

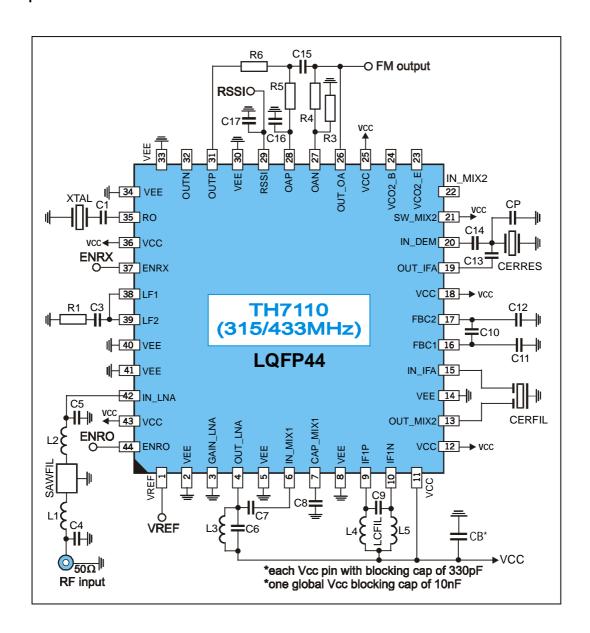


Fig. 4: Test circuit for FM reception

FM test circuit component list to Fig. 4

Part	Size	Value / Type	Tolerance	Description		
C1	0805	15 pF	±10%	crystal series capacitor		
C3	0805	1 nF	±10%	loop filter capacitor		
C4	0603	3.3 pF	±5%	capacitor to match to SAW filter input		
C5	0603	3.3 pF	±5%	capacitor to match to SAW filter output		
C6	0603	4.7 pF	±5%	LNA output tank capacitor		
C7	0603	2.2 pF	±5%	MIX1 input matching capacitor		
C8	0603	330 pF	±10%	MIX1 blocking capacitor		
C9	0603	27 pF	±5%	IF1 tank capacitor		
C10	0805	33 nF	±10%	IFA feedback capacitor		
C11	0603	1 nF	±10%	IFA feedback capacitor		
C12	0603	1 nF	±10%	IFA feedback capacitor		
C13	0603	1.5 pF	±5%	DEMOD phase-shift capacitor		
C14	0603	680 pF	±10%	DEMOD coupling capacitor		
CP	0805	10 – 12 pF	±5%	CERRES parallel capacitor		
C15	0805	100 pF	±5%	sallen-Key low-pass filter capacitor, to set cut-off frequency		
C16	0805	100 pF	±5%	sallen-Key low-pass filter capacitor, to set cut-off frequency		
C17	0603	330 pF	±10%	RSSI output low-pass capacitor		
R1	0805	10 kΩ	±10%	loop filter resistor		
R3	0805	12 kΩ	±5%	sallen-key filter resistor, to set desired filter characteristic		
R4	0805	6.8 kΩ	±5%	sallen-key filter resistor, to set desired filter characteristic		
R5	0805	33 kΩ	±5%	sallen-key filter resistor, to set cut-off frequency		
R6	0805	33 kΩ	±5%	sallen-key filter resistor, to set cut-off frequency		
L1	0603	33 nH	±5%	inductor to match SAW filter		
L2	0603	33 nH	±5%	inductor to match SAW filter		
L3	0603	15 nH	±5%	LNA output tank inductor		
L4	0603	100 nH	±5%	IF1 tank inductor		
L5	0603	100 nH	±5%	IF1 tank inductor		
XTAL	HC49- SMD	23.49444 MHz @ RF = 433.6 MHz	±25ppm calibra- tion ±30ppm temp.	fundamental-mode crystal, C_{load} = 10 pF to 15pF, $C_{0, max}$ = 7 pF, $R_{m, max}$ = 50 Ω		
SAWFIL	QCC8C	B3555	B _{3dB} = 860 kHz	low-loss SAW filter from EPCOS		
		@ RF = 433.6 MHz	$\pm 100 \text{ kHz}$ (f ₀ = 433.92 MHz)			
CERFIL	leaded type	SFE10.7MFP @ B _{IF2} = 40 kHz	TBD	ceramic filter from Murata		
	SMD type	SFECV10.7MJS-A @ B _{IF2} = 150 kHz	±40 kHz			
CERRES	SMD type	CDACV10.7MG18-A		ceramic demodulator tank from Murata		

NIP - not in place, may be used optionally



ASK Reception

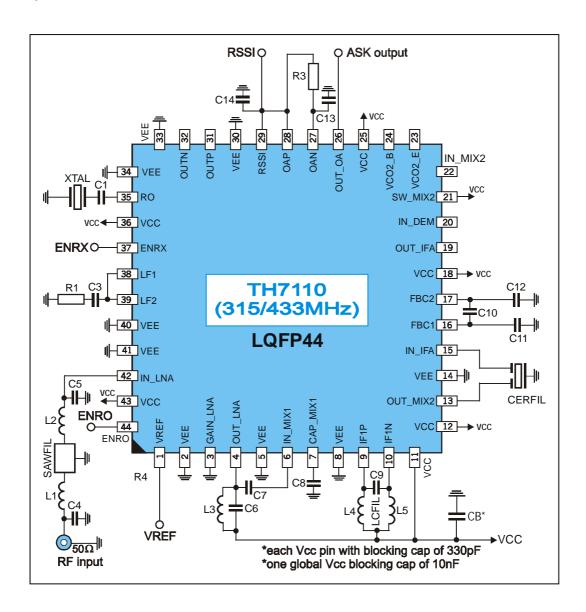


Fig. 5: Test circuit for ASK reception

ASK test circuit component list to Fig. 5

Part	Size	Value / Type	Tolerance	Description		
C1	0805	15 pF	±10%	crystal series capacitor		
C3	0805	1 nF	±10%	loop filter capacitor		
C4	0603	3.3 pF	±5%	capacitor to match to SAW filter input		
C5	0603	3.3 pF	±5%	capacitor to match to SAW filter output		
C6	0603	4.7 pF	±5%	LNA output tank capacitor		
C7	0603	2.2 pF	±5%	MIX1 input matching capacitor		
C8	0603	330 pF	±10%	MIX1 blocking capacitor		
C9	0805	27 pF	±5%	IF1 tank capacitor		
C10	0805	33 nF	±10%	IFA feedback capacitor		
C11	0603	1 nF	±10%	IFA feedback capacitor		
C12	0603	1 nF	±10%	IFA feedback capacitor		
C13	0805	1 nF to 10 nF	±10%	ASK data slicer capacitor, depending on data rate		
C14	0603	330 pF	±10%	RSSI output low-pass capacitor		
R1	0805	10 kΩ	±10%	loop filter resistor		
R3	0603	100 kΩ	±5%	ASK data slicer resistor, depending on data rate		
L1	0603	33 nH	±5%	inductor to match SAW filter		
L2	0603	33 nH	±5%	inductor to match SAW filter		
L3	0603	15 nH	±5%	LNA output tank inductor		
L4	0603	100 nH	±5%	IF1 tank inductor		
L5	0603	100 nH	±5%	IF1 tank inductor		
XTAL	HC49-	23.49444 MHz	±25ppm calibra-	fundamental-mode crystal, C _{load} = 10 pF to 15pF,		
	SMD	@ RF = 433.6 MHz	tion	$C_{0, \text{ max}} = 7 \text{ pF}, R_{\text{m, max}} = 50 \Omega$		
			±30ppm temp.			
SAWFIL	QCC8C	B3555	$B_{3dB} = 860 \text{ kHz}$	low-loss SAW filter from EPCOS		
		@ RF = 433.6 MHz	±100 kHz			
CERFIL	leaded	SFE10.7MFP	$(f_0 = 433.92 \text{ MHz})$	ceramic filter from Murata		
OLKEIL	type	@ B _{IF2} = 40 kHz	100	Ceramic liner nom wurata		
	SMD type	SFECV10.7MJS-A	±40 kHz			
	,,,,,	@ $B_{IF2} = 150 \text{ kHz}$	52			

NIP – not in place, may be used optionally



Package Dimensions

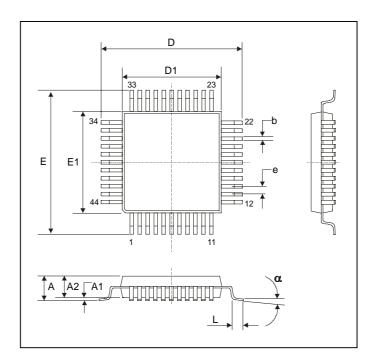


Fig. 6: LQFP44 (Low Quad Flat Package)

All Dime	All Dimension in mm, coplanaríty < 0.1mm									
	E1, D1	Α	A1	A2	е	b	L	E, D	α	
min			0.05	1.35		0.30	0.45		0°	
	10.00				0.8			12.00		
max		1.60	0.15	1.45		0.45	0.75		7°	
All Dime	nsion in in	ich, cop	lanaríty <	< 0.004"						
min			0.002	0.053		0.012	0.018		0°	
	0.394				0.031			0.472		
max		0.630	0.006	0.057		0.018	0.030		7°	

Your Notes

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